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**Kim et al.**

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(54) **METHOD FOR FABRICATING SURFACE ACOUSTIC WAVE FILTER PACKAGES AND PACKAGE SHEET USED THEREIN**

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See application file for complete search history.

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(57) **ABSTRACT**

A method for fabricating Surface Acoustic Wave filter packages uses a package sheet having an outline pattern and anti-bur holes. In the package sheet for a Surface Acoustic Wave filter package, the outline pattern is formed along outer peripheries of chip mounting areas where a plurality of SAW filter chips are to be mounted. The outline pattern is contacted with a metal shield layer formed on the SAW filter chips and a predetermined region of the package sheet. Circular anti-bur holes are located at the corners of the chip mounting areas and on cutting lines along which the sheet is to be singulated into individual SAW filter packages.

**11 Claims, 6 Drawing Sheets**

